

CD4028BMS

December 1992

CMOS BCD-To-Decimal Decoder

Features

- High Voltage Type (20V Rating)
- BCD-to-Decimal Decoding or Binary-to-Octal Decoding
- · High Decoded Output Drive Capability
- "Positive Logic" Inputs and Outputs Decoded Outputs Go High On Selection
- Medium-Speed Operation
 - tPHL, tPLH = 80ns (typ) at VDD = 10V
- Standardized Symmetrical Output Characteristics
- 100% Tested For Quiescent Current at 20V
- Maximum Input Current of 1μA at 18V Over Full Package-Temperature Range;
 - 100nA at 18V and +25°C
- Noise Margin (Over Full Package Temperature Range):
 - 1V at VDD = 5V
 - 2V at VDD = 10V
 - 2.5V at VDD = 15V
- 5V, 10V and 15V Parametric Ratings
- Meets All Requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications

- Code Conversion
- Indication-Tube Decoder
- Address Decoding Memory Selection Control

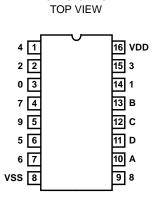
Description

CD4028BMS types are BCD-to-decimal or binary-to-octal decoders consisting of buffering on all 4 inputs, decoding logic gates, and 10 output buffers. A BCD code applied to the four inputs, A to D, results in a high level at the selected one of 10 decimal decoded outputs. Similarly, a 3-bit binary code applied to inputs A through C is decoded in octal code at output 0 to 7 if D = "0". High drive capability is provided at all outputs to enhance dc and dynamic performance in high fan-out applications.

The CD4028BMS is supplied in these 16-lead outline packages:

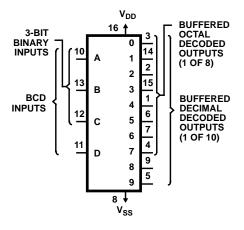
Braze Seal DIP H4S Frit Seal DIP H1E Ceramic Flatpack H3X

Pinout



CD4028BMS

Functional Diagram



Reliability Information Absolute Maximum Ratings Thermal Resistance nermal Resistance θ_{ja} Ceramic DIP and FRIT Package 80° C/W DC Supply Voltage Range, (VDD) -0.5V to +20V $_{20^{o}\text{C/W}}^{\theta_{jc}}$ (Voltage Referenced to VSS Terminals) Flatpack Package 70°C/W Input Voltage Range, All Inputs -0.5V to VDD +0.5V 20°C/W Maximum Package Power Dissipation (PD) at +125°C DC Input Current, Any One Input±10mA Operating Temperature Range.....-55°C to +125°C For TA = -55° C to $+100^{\circ}$ C (Package Type D, F, K).....500mW For TA = $+100^{\circ}$ C to $+125^{\circ}$ C (Package Type D, F, K) Derate Package Types D, F, K, H Storage Temperature Range (TSTG) -65°C to +150°C Linearity at 12mW/°C to 200mW Lead Temperature (During Soldering) +265°C Device Dissipation per Output Transistor 100mW At Distance 1/16 \pm 1/32 Inch (1.59mm \pm 0.79mm) from case for For TA = Full Package Temperature Range (All Package Types) 10s Maximum

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

				GROUP A		LIN	IITS	
PARAMETER	SYMBOL	CONDITIONS (NOTE 1)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 20V, VIN = VD	D or GND	1	+25°C	-	10	μΑ
				2	+125°C	-	1000	μΑ
		VDD = 18V, VIN = VD	D or GND	3	-55°C	-	10	μΑ
Input Leakage Current	IIL	VIN = VDD or GND	VDD = 20	1	+25°C	-100	-	nA
				2	+125°C	-1000	-	nA
			VDD = 18V	3	-55°C	-100	-	nA
Input Leakage Current	IIH	VIN = VDD or GND	VDD = 20	1	+25°C	-	100	nA
				2	+125°C	-	1000	nA
		VDD = 18V		3	-55°C	-	100	nA
Output Voltage	VOL15	VDD = 15V, No Load	•	1, 2, 3	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH15	VDD = 15V, No Load	(Note 3)	1, 2, 3	+25°C, +125°C, -55°C	14.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.	.4V	1	+25°C	0.53	-	mA
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0	0.5V	1	+25°C	1.4	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1	1.5V	1	+25°C	3.5	-	mA
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.	.6V	1	+25°C	-	-0.53	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.	.5V	1	+25°C	-	-1.8	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9	9.5V	1	+25°C	-	-1.4	mA
Output Current (Source)	IOH15	VDD = 15V, VOUT = 1	13.5V	1	+25°C	-	-3.5	mA
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10	μΑ	1	+25°C	-2.8	-0.7	V
P Threshold Voltage	VPTH	VSS = 0V, IDD = 10μ/	4	1	+25°C	0.7	2.8	V
Functional	F	VDD = 2.8V, VIN = VI	DD or GND	7	+25°C	VOH>	VOL <	V
		VDD = 20V, VIN = VD	D or GND	7	+25°C	VDD/2	VDD/2	
		VDD = 18V, VIN = VD	D or GND	8A	+125°C			
		VDD = 3V, VIN = VDD	or GND	8B	-55°C			
Input Voltage Low (Note 2)	VIL	VDD = 5V, VOH > 4.5	V, VOL < 0.5V	1, 2, 3	+25°C, +125°C, -55°C	-	1.5	V
Input Voltage High (Note 2)	VIH	VDD = 5V, VOH > 4.5	V, VOL < 0.5V	1, 2, 3	+25°C, +125°C, -55°C	3.5	-	V
Input Voltage Low (Note 2)	VIL	VDD = 15V, VOH > 13 VOL < 1.5V	3.5V,	1, 2, 3	+25°C, +125°C, -55°C	-	4	V
Input Voltage High (Note 2)	VIH	VDD = 15V, VOH > 13 VOL < 1.5V	3.5V,	1, 2, 3	+25°C, +125°C, -55°C	11	-	V

NOTES: 1. All voltages referenced to device GND, 100% testing being 3. For accuracy, voltage is measured differentially to VDD. Limit implemented.

is 0.050V max.

2. Go/No Go test with limits applied to inputs.

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

			GROUP A		LIM		
PARAMETER	SYMBOL	CONDITIONS (NOTE 1, 2)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Propagation Delay	TPHL VDD = 5V, VIN = VDD or GND		9	+25°C	-	350	ns
	TPLH		10, 11	+125°C, -55°C	-	473	ns
Transition Time	TTHL	VDD = 5V, VIN = VDD or GND	9	+25°C	-	200	ns
	TTLH		10, 11	+125°C, -55°C	-	270	ns

NOTES:

- 1. CL = 50pF, RL = 200K, Input TR, TF < 20ns.
- 2. -55° C and $+125^{\circ}$ C limits guaranteed, 100% testing being implemented.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIN		
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 5V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	5	μΑ
				+125°C	-	150	μА
		VDD = 10V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	10	μА
				+125°C	-	300	μА
		VDD = 15V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	10	μА
				+125°C	-	600	μА
Output Voltage	VOL	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOL	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	4.95	-	V
Output Voltage	VOH	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	9.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.4V	1, 2	+125°C	0.36	-	mA
				-55°C	0.64	-	mA
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0.5V	1, 2	+125°C	0.9	-	mA
				-55°C	1.6	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1.5V	1, 2	+125°C	2.4	-	mA
				-55°C	4.2	-	mA
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.6V	1, 2	+125°C	-	-0.36	mA
				-55°C	-	-0.64	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.5V	1, 2	+125°C	-	-1.15	mA
				-55°C	-	-2.0	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9.5V	1, 2	+125°C	-	-0.9	mA
				-55°C	-	-1.6	mA
Output Current (Source)	IOH15	VDD =15V, VOUT = 13.5V	1, 2	+125°C	-	-2.4	mA
				-55°C	-	-4.2	mA
Input Voltage Low	VIL	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	-	3	V
Input Voltage High	VIH	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	7	-	V

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

					LIM		
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Propagation Delay	TPHL	VDD = 10V	1, 2, 3	+25°C	-	160	ns
	TPLH	VDD = 15V	1, 2, 3	+25°C	-	120	ns
Transition Time	TTHL	VDD = 10V	1, 2, 3	+25°C	-	100	ns
	TTLH	VDD = 15V	1, 2, 3	+25°C	-	80	ns
Input Capacitance	CIN		1, 2	+25°C	-	7.5	pF

NOTES:

- 1. All voltages referenced to device GND.
- 2. The parameters listed on Table 3 are controlled via design or process and are not directly tested. These parameters are characterized on initial design release and upon design changes which would affect these characteristics.
- 3. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 20V, VIN = VDD or GND	1, 4	+25°C	-	25	μΑ
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10μA	1, 4	+25°C	-2.8	-0.2	V
N Threshold Voltage Delta	ΔVTN	VDD = 10V, ISS = -10μA	1, 4	+25°C	-	±1	V
P Threshold Voltage	VTP	VSS = 0V, IDD = 10μA	1, 4	+25°C	0.2	2.8	V
P Threshold Voltage Delta	ΔVΤΡ	VSS = 0V, IDD = 10μA	1, 4	+25°C	-	±1	V
Functional	F	VDD = 18V, VIN = VDD or GND	1	+25°C	VOH >	VOL <	V
		VDD = 3V, VIN = VDD or GND			VDD/2	VDD/2	
Propagation Delay Time	TPHL TPLH	VDD = 5V	1, 2, 3, 4	+25°C	-	1.35 x +25°C Limit	ns

NOTES: 1. All voltages referenced to device GND.

3. See Table 2 for +25°C limit.

2. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

4. Read and Record

TABLE 5. BURN-IN AND LIFE TEST DELTA PARAMETERS +25°C

PARAMETER	SYMBOL	DELTA LIMIT
Supply Current - MSI-2	IDD	± 1.0μA
Output Current (Sink)	IOL5	± 20% x Pre-Test Reading
Output Current (Source)	IOH5A	± 20% x Pre-Test Reading

TABLE 6. APPLICABLE SUBGROUPS

CONFORMANCE GROUP	MIL-STD-883 METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (Pre Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 1 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 2 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note 1)	100% 5004	1, 7, 9, Deltas	
Interim Test 3 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note 1)	100% 5004	1, 7, 9, Deltas	

TABLE 6. APPLICABLE SUBGROUPS (Continued)

CONFO	RMANCE GROUP	MIL-STD-883 METHOD	GROUP A SUBGROUPS	READ AND RECORD
Final Test		100% 5004	2, 3, 8A, 8B, 10, 11	
Group A		Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B	Subgroup B-5	Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas	Subgroups 1, 2, 3, 9, 10, 11
Subgroup B-6		Sample 5005	1, 7, 9	
Group D		Sample 5005	1, 2, 3, 8A, 8B, 9	Subgroups 1, 2 3

NOTE: 1.5% Parameteric, 3% Functional; Cumulative for Static 1 and 2.

TABLE 7. TOTAL DOSE IRRADIATION

	MIL-STD-883	TE	ST	READ AND RECORD				
CONFORMANCE GROUPS	METHOD	PRE-IRRAD	POST-IRRAD	PRE-IRRAD	POST-IRRAD			
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4			

TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS

					OSCILLATOR					
FUNCTION	OPEN	GROUND	VDD	9V ± -0.5V	50kHz	25kHz				
Static Burn-In 1 Note 1	1 - 7, 9, 14, 15	8, 10 - 13	16							
Static Burn-In 2 Note 1	1 - 7, 9, 14, 15	8	10 - 13, 16							
Dynamic Burn- In Note 1	-	8	16	1 - 7, 9, 14, 15	10, 12, 13	11				
Irradiation Note 2	1 - 7, 9, 14, 15	8	10 - 13, 16							

NOTE:

- 1. Each pin except VDD and GND will have a series resistor of 10K $\pm\,5\%,$ VDD = 18V $\pm\,0.5V$
- 2. Each pin except VDD and GND will have a series resistor of 47K \pm 5%; Group E, Subgroup 2, sample size is 4 dice/wafer, 0 failures, VDD = $10V \pm 0.5V$

Logic Diagram

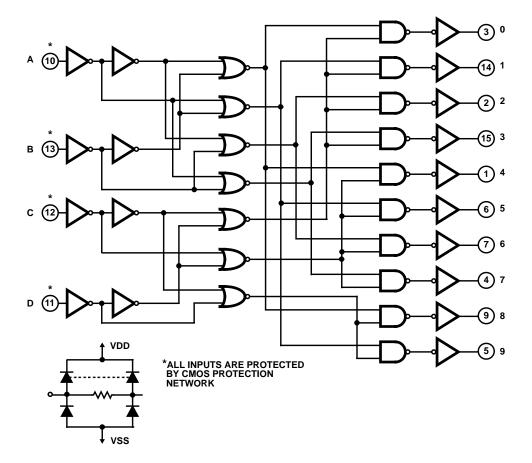


TABLE 1. TRUTH TABLE

D	С	В	Α	0	1	2	3	4	5	6	7	8	9
0	0	0	0	1	0	0	0	0	0	0	0	0	0
0	0	0	1	0	1	0	0	0	0	0	0	0	0
0	0	1	0	0	0	1	0	0	0	0	0	0	0
0	0	1	1	0	0	0	1	0	0	0	0	0	0
0	1	0	0	0	0	0	0	1	0	0	0	0	0
0	1	0	1	0	0	0	0	0	1	0	0	0	0
0	1	1	0	0	0	0	0	0	0	1	0	0	0
0	1	1	1	0	0	0	0	0	0	0	1	0	0
1	0	0	0	0	0	0	0	0	0	0	0	1	0
1	0	0	1	0	0	0	0	0	0	0	0	0	1
1	0	1	0	0	0	0	0	0	0	0	0	0	0
1	0	1	1	0	0	0	0	0	0	0	0	0	0
1	1	0	0	0	0	0	0	0	0	0	0	0	0
1	1	0	1	0	0	0	0	0	0	0	0	0	0
1	1	1	0	0	0	0	0	0	0	0	0	0	0
1	1	1	1	0	0	0	0	0	0	0	0	0	0

1 = HIGH LEVEL

0 = LOW LEVEL

Typical Performance Characteristics

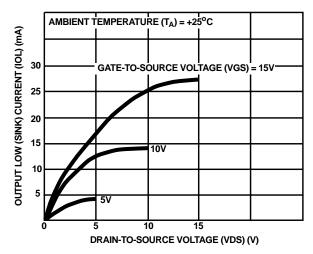


FIGURE 1. TYPICAL OUTPUT LOW (SINK) CURRENT CAPACITANCE

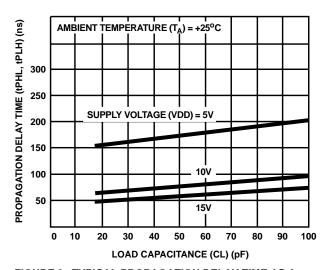


FIGURE 3. TYPICAL PROPAGATION DELAY TIME AS A FUNCTION OF LOAD CAPACITANCE

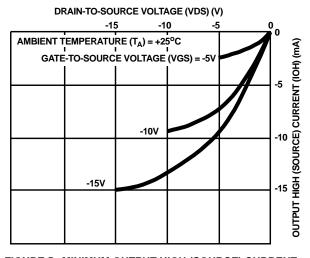


FIGURE 5. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

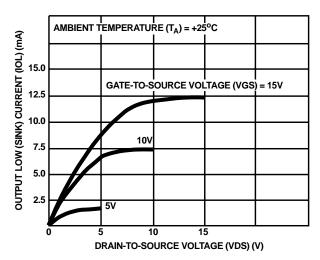


FIGURE 2. MINIMUM OUTPUT LOW (SINK) CURRENT CAPACITANCE

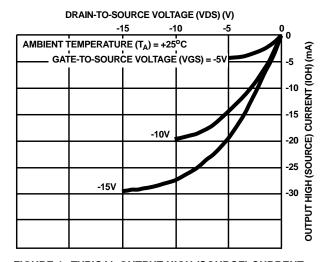


FIGURE 4. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

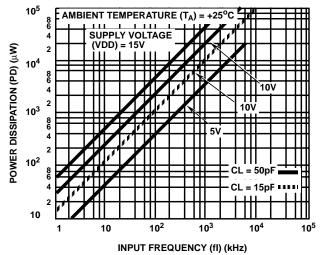


FIGURE 6. TYPICAL DYNAMIC POWER DISSIPATION AS A FUNCTION OF INPUT FREQUENCY

Typical Performance Characteristics (Continued)

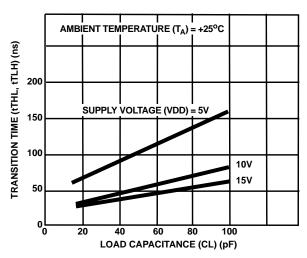


FIGURE 7. TYPICAL TRANSITION TIME AS A FUNCTION OF LOAD CAPACITANCE

Typical Applications

The circuit shown in Figure 8 converts any 4-bit code to a decimal or hexadecimal code. Table 2 shows a number of codes and the decimal or hexadecimal number in these codes which must be applied to the input terminals of the CD4028BMS to select a particular output. For example: in order to get a high on output number 8 the input must be either an 8 expressed in 4-bit Binary code, a 15 expressed in 4-Bit Gray code, or a 5 expressed in Excess-3 code.

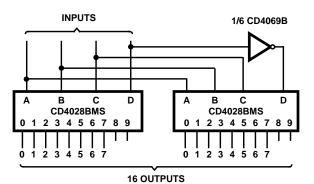


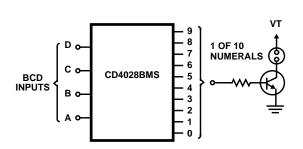
FIGURE 8. CODE CONVERSION CIRCUIT

TABLE 2. CODE CONVERSION CHART

					IN	PUT C	ODES																		
	INP	UTS		HE. DEC	XA- IMAL		DECIN	IAL		OUTPUT NUMBER															
D	С	В	A	4-BIT BINARY	4-BIT GRAY	EXCESS-3	EXCESS-3 GRAY	AIKEN	4-2-2-1	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
0	0	0	0	0	0			0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1			1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	1	0	2	3		0	2	2	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	1	1	3	2	0	3	3		0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0
0	1	0	0	4	7	1	4	4		0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0
0	1	0	1	5	6	2			3	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0
0	1	1	0	6	4	3	1		4	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
0	1	1	1	7	5	4	2			0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
1	0	0	0	8	15	5				0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0
1	0	0	1	9	14	6			5	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0
1	0	1	0	10	12	7	9		6	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0

TABLE 2. CODE CONVERSION CHART (Continued)

				INPUT CODES																					
INPUTS			HEXA- DECIMAL		DECIMAL				OUTPUT NUMBER																
D	С	В	А	4-BIT BINARY	4-BIT GRAY	EXCESS-3	EXCESS-3 GRAY	AIKEN	4-2-2-1	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
1	0	1	1	11	13	8		5		0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0
1	1	0	0	12	8	9	5	6		0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0
1	1	0	1	13	9		6	7	7	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0
1	1	1	0	14	11		8	8	8	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
1	1	1	1	15	10		7	9	9	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1



*(TRADEMARK) BURROUGHS CORP.

TUBE REQUIREMENTS

TYPE	=	VT(Vdc)	NUMERAL mA/						
11171	=	VI(Vuc)	IIIA/						
BURROUGHS	B4081	170	14						
	B4336/ 718	170	2						
	B4032	170	14						
	B4021	120	14						
TRANSISTOR CHARACTERISTICS									
Leakage with transistor cutoff ≤ 0.05mA									

V(BR)CEO ≥ 70V

FIGURE 9. NEON READOUT (NIXIE TUBE*) DISPLAY APPLICATION

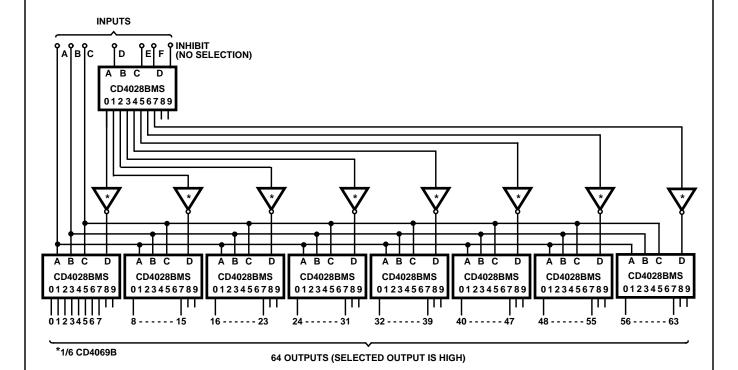
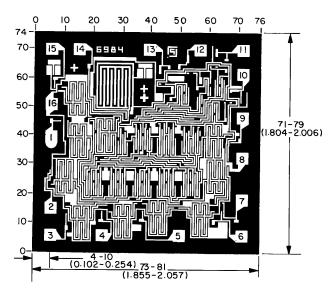


FIGURE 10. 6-BIT BINARY TO 1-OF-64 ADDRESS DECODER

Chip Dimensions and Pad Layout



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch)

METALLIZATION: Thickness: 11kÅ - 14kÅ, AL.

PASSIVATION: 10.4kÅ - 15.6kÅ, Silane

BOND PADS: 0.004 inches X 0.004 inches MIN **DIE THICKNESS:** 0.0198 inches - 0.0218 inches

All Intersil semiconductor products are manufactured, assembled and tested under ISO9000 quality systems certification.

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